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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c63-20i-sp

Pin Diagrams PDIP, SOIC, Windowed CERDIP SDIP, SOIC, SSOP, Windowed CERDIP (300 mil) 18 → RA1 MCI R/Vpp RA3 ← 2 RA4/T0CKI ← 3 RA0 ← □ 2 27 ☐ → RB6 26 ☐ → RB5 17 → RA0 RA1 **←** ► □ 3 16 → OSC1/CLKIN 25 □ → RB4 MCLR/VPP → 4 15 → OSC2/CLKOUT RA3 **→** □ 5 24 ☐ → RB3 Vss --- □ 5 RA4/T0CKI ← □ 6 23 ☐ → RB2 RA5/SS → □ 7 Vss → □ 8 22 ☐ → RB1 21 ☐ → RB0/INT 13 ←→ RB7 RB0/INT ← 6 RB1 **→** 7 12 ←→ RB6 20 - VDD 19 - VSS RB2 → □ 8 11 → RB5 RC0/T1OSI/T1CKI ← ☐ 11 RC1/T1OSO ← ☐ 12 RC2/CCP1 ← ☐ 13 RB3 **→** 9 RB4 16 ☐ ←→ RC5/SDO PIC16C61 RC3/SCK/SCL ← ► □ 14 15 ☐ ←→ RC4/SDI/SDA **PIC16C62** SDIP, SOIC, SSOP, Windowed CERDIP (300 mil) SDIP, SOIC, Windowed CERDIP (300 mil) R/VPP - C RA0 - C RA1 - C RA2 - C MCI B/Vpp -28 ☐ ←→ RB7 MCI B/Vpp -□ ←→ RB6 □ - RB6 RA1 → □ 3 26 ☐ ←→ RB5 26 ☐ ←→ RB5 RA2 ▼ ► □ 4 25 ☐ ←→ RB4 4 25 ☐ ←→ RB4 RA3 **→** 5 RA4/T0CKI **→** 6 24 ☐ → RB3 23 ☐ → RB2 24 ☐ → RB3 23 ☐ → RB2 RA5/SS → □ 7 22 ☐ → RB1 Vss — **-** □ 8 21 □ - RB0/INT OSC1/CLKIN → 9 OSC2/CLKOUT ← 10 10 10 19 ☐ **→** Vss RC0/T1OSO/T1CKI - 11 RC1/T1OSI - 12 RC2/CCP1 - 13 RC0/T1OSO/T1CKI ---18 ☐ ← ► RC7/RX/DT 17 ☐ → RC6 12 17 ☐ → RC6/TX/CK RC2/CCP1 → ► 16 → BC5/SDO 13 16 - RC5/SDO RC3/SCK/SCL ← ► RC3/SCK/SCL → □ 14 15 T → RC4/SDI/SDA 15 RC4/SDI/SDA PIC16C62A PIC16C63 PIC16CR62 PIC16CR63 **PIC16C66** PDIP, Windowed CERDIP MCLR/Vpp → □ 1 40 1 → BR7 MCLB/Vpp → 1 40 1 → BB7 39 ☐ < ► RB6 38 ☐ < ► RB5 RA0 ▼ ► □ 2 RA1 → □ 3 37 RB4 36 RB3 35 RB2 34 RB1 RA2 ▼ ► □ 4 36 ☐ < ► RB3 35 ☐ < ► RB2 BA3 ▼ ► □ 5 RA4/T0CKI → □ 6 RA5/SS → □ 7 33 ☐ → ► RB0/INT RE0/RD → □ 8 RE1/WR → □ 9 RE2/CS → □ 10 26 → RC7/RX/DT PIC16C64A PIC16C64 **PIC16C65** PIC16CR64 PIC16C65A

PIC16CR65 PIC16C67

4.2.2.7 PIR2 REGISTER

Applicable Devices
61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

This register contains the CCP2 interrupt flag bit.

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-21: PIR2 REGISTER (ADDRESS 0Dh)

U-0 U-0 U-0 U-0 U-0 U-0 U-0 R/W-0 CCP2IF bit7

R = Readable bit W = Writable bit U = Unimplemented bit,

bit 7-1: Unimplemented: Read as '0'

read as '0' n = Value at POR reset

bit 0: CCP2IF: CCP2 Interrupt Flag bit

Capture Mode

1 = A TMR1 register capture occurred (must be cleared in software)

0 = No TMR1 register capture occurred

Compare Mode

1 = A TMR1 register compare match occurred (must be cleared in software)

0 = No TMR1 register compare match occurred

PWM Mode

Unused in this mode

Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

Note:

11.2.1 OPERATION OF SSP MODULE IN SPI MODE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- · Serial Data Out (SDO)
- · Serial Data In (SDI)
- · Serial Clock (SCK)

Additionally a fourth pin may be used when in a slave mode of operation:

Slave Select (SS)

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>). These control bits allow the following to be specified:

- · Master Mode (SCK is the clock output)
- · Slave Mode (SCK is the clock input)
- Clock Polarity (Output/Input data on the Rising/ Falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

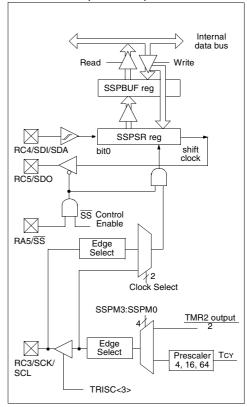
The SSP consists of a transmit/receive Shift Register (SSPSR) and a Buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR, until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the Buffer Full bit, BF (SSPSTAT<0>) and flag bit SSPIF are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit, WCOL (SSPCON<7>) will be set. User software must clear bit WCOL so that it can be determined if the following write(s) to the SSPBUF completed successfully. When the application software is expecting to receive valid data, the SSPBUF register should be read before the next byte of data to transfer is written to the SSPBUF register. The Buffer Full bit BF (SSPSTAT<0>) indicates when the SSPBUF register has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the SSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF register must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 11-1 shows the loading of the SSPBUF (SSPSR) register for data transmission. The shaded instruction is only required if the received data is meaningful.

EXAMPLE 11-1: LOADING THE SSPBUF (SSPSR) REGISTER

		BSF	STATUS,	RP0	;Specify Bank 1
L(OOP	BTFSS	SSPSTAT,	BF	;Has data been
					;received
					;(transmit
					;complete)?
		GOTO	LOOP		; No
		BCF	STATUS,	RP0	;Specify Bank 0
		MOVF	SSPBUF,	W	;W reg = contents
					;of SSPBUF
		MOVWF	RXDATA		;Save in user RAM
		MOVF	TXDATA,	W	;W reg = contents
					; of TXDATA
		MOVWF	SSPBUF		;New data to xmit

The block diagram of the SSP module, when in SPI mode (Figure 11-3), shows that the SSPSR register is not directly readable or writable, and can only be accessed from addressing the SSPBUF register. Additionally, the SSP status register (SSPSTAT) indicates the various status conditions.

FIGURE 11-3: SSP BLOCK DIAGRAM (SPI MODE)



11.4.2 ADDRESSING I2C DEVICES

There are two address formats. The simplest is the 7-bit address format with a $R\overline{W}$ bit (Figure 11-15). The more complex is the 10-bit address with a $R\overline{W}$ bit (Figure 11-16). For 10-bit address format, two bytes must be transmitted with the first five bits specifying this to be a 10-bit address.

FIGURE 11-15: 7-BIT ADDRESS FORMAT

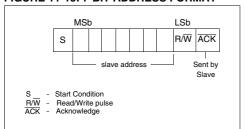
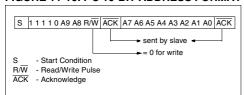


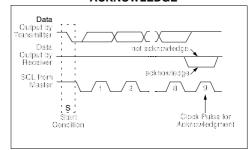
FIGURE 11-16: I2C 10-BIT ADDRESS FORMAT



11.4.3 TRANSFER ACKNOWLEDGE

All data must be transmitted per byte, with no limit to the number of bytes transmitted per data transfer. After each byte, the slave-receiver generates an acknowledge bit (\overline{ACK}) (Figure 11-17). When a slave-receiver doesn't acknowledge the slave address or received data, the master must abort the transfer. The slave must leave SDA high so that the master can generate the STOP condition (Figure 11-14).

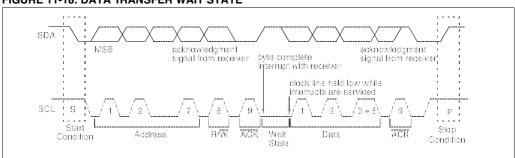
FIGURE 11-17: SLAVE-RECEIVER ACKNOWLEDGE



If the master is receiving the data (master-receiver), it generates an acknowledge signal for each received byte of data, except for the last byte. To signal the end of data to the slave-transmitter, the master does not generate an acknowledge (not acknowledge). The slave then releases the SDA line so the master can generate the STOP condition. The master can also generate the STOP condition during the acknowledge pulse for valid termination of data transfer.

If the slave needs to delay the transmission of the next byte, holding the SCL line low will force the master into a wait state. Data transfer continues when the slave releases the SCL line. This allows the slave to move the received data or fetch the data it needs to transfer before allowing the clock to start. This wait state technique can also be implemented at the bit level, Figure 11-18. The slave will inherently stretch the clock, when it is a transmitter, but will not when it is a receiver. The slave will have to clear the SSPCON<4> bit to enable clock stretching when it is a receiver.

FIGURE 11-18: DATA TRANSFER WAIT STATE



12.1 USART Baud Rate Generator (BRG)

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

Fosc = 16 MHz Desired Baud Rate = 9600 BRGH = 0 SYNC = 0

EXAMPLE 12-1: CALCULATING BAUD RATE FRROR

Desired Baud rate = Fosc / (64 (X + 1))

9600 = 16000000 / (64 (X + 1)) $X = \lfloor 25.042 \rfloor = 25$

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

Error = (Calculated Baud Rate - Desired Baud Rate)

Desired Baud Rate

= (9615 - 9600) / 9600

= 0.16%

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X+1)) equation can reduce the baud rate error in some cases.

Note: For the PIC16C63/R63/65/65A/R65 the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C66/67.

Writing a new value to the SPBRG register, causes the BRG timer to be reset (or cleared), this ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

TABLE 12-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = Fosc/(64(X+1))	Baud Rate = Fosc/(16(X+1))
1	(Synchronous) Baud Rate = Fosc/(4(X+1))	N/A

X = value in SPBRG (0 to 255)

TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	-	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	_	FERR	OERR	RX9D	0000 -00x	0000 -00x
99h SPBRG Baud Rate Generator Register										0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.



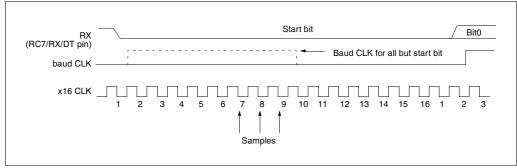


TABLE 13-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS (Cont.'d)

Register						Appli	cab	le De	vices	\$					Power-on Reset Brown-out Reset	MCLR Reset during: - normal operation - SLEEP WDT Reset	Wake-up via interrupt or WDT Wake-up
TRISD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1111	1111 1111	uuuu uuuu
TRISE	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 -111	0000 -111	uuuu -uuu
PIE1	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00 0000	00 0000	uu uuuu
	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
PIE2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0	0	u
PCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0u	uu	uu
FCON	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0-	u-	u-
PR2	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	1111 1111	1111 1111	1111 1111
SSPADD	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	00 0000	00 0000	uu uuuu
TXSTA	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 -010	0000 -010	uuuu -uuu
SPBRG	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67	0000 0000	0000 0000	uuuu uuuu

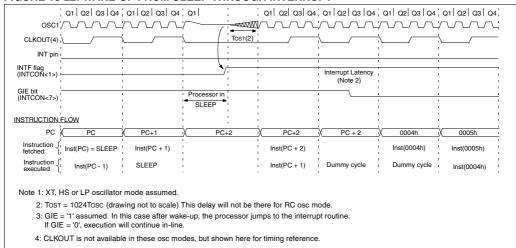
 $[\]label{eq:local_$

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

^{2:} When the wake-up is due to an interrupt and the global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

^{3:} See Table 13-10 and Table 13-11 for reset value for specific conditions.

FIGURE 13-22: WAKE-UP FROM SLEEP THROUGH INTERRUPT



13.9 Program Verification/Code Protection

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

13.10 ID Locations

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

13.11 <u>In-Circuit Serial Programming</u>

Αp	Applicable Devices												
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding pins RB6 and RB7 low while raising the MCLR (VPP) pin from VIL to VIHH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device in program/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

FIGURE 13-23: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION

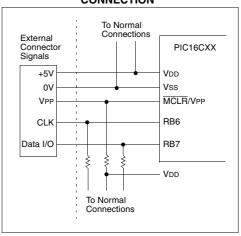


TABLE 14-2: PIC16CXX INSTRUCTION SET

Mnemonic	,	Description	Cycles		14-Bit	Opcode	е	Status	Notes
Operands				MSb			LSb	Affected	
BYTE-ORIE	ENTED	FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	0.0	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	0.0	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	0.0	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	0.0	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	0.0	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	0.0	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	0.0	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	0.0	0000	lfff	ffff		
NOP	-	No Operation	1	0.0	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	0.0	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	0.0	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	0.0	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	0.0	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIEN	TED FIL	E REGISTER OPERATIONS							
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL A	ND CO	NTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	0.0	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00x	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	0.0	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., MOUF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

^{2:} If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

^{3:} If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

INCFSZ	Increme	nt f, Skip	if 0	
Syntax:	[label]	INCFSZ	f,d	
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27		
Operation:	(f) + 1 \rightarrow skip if res	•	ion),	
Status Affected:	None			
Encoding:	00	1111	dfff	ffff
Description:	The conte mented. If the W regi placed bad If the resu executed. cuted insta- tion.	'd' is 0 the ister. If 'd' i ck in regist It is 1, the If the resu	e result is p s 1 the res ter 'f'. next instru It is 0, a NO	olaced in sult is oction is OP is exe-
Words:	1			
Cycles:	1(2)			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write to destination
If Skip:	(2nd Cyc	le)		
	Q1	Q2	Q3	Q4
	No- Operation	No- Operation	No- Operation	No- Operation
Example	HERE	INCFS GOTO UE •	Z CI LO	NT, 1 OP
	Before In PC After Inst CNT if CNT PC if CNT PC	= add ruction = CN7 = 0, = add ≠ 0,	ress HERE + 1 ress CONT ress HERE	

IORLW	Inclusive	OR Lite	eral with	W			
Syntax:	[label]	IORLW	k				
Operands:	$0 \le k \le 25$	55					
Operation:	(W) .OR.	$k \rightarrow (W)$)				
Status Affected:	Z						
Encoding:	11	1000	kkkk	kkkk			
Description:	The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.						
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
	Decode	Read literal 'k'	Process data	Write to W			
Example	IORLW	0x35					

Before Instruction

After Instruction

W = 0x9A

W = 0xBF Z = 1

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and DC CHARACTERISTICS 0°C < TA < +70°C for commercial Operating voltage VDD range as described in DC spec Section 17.1 and Section 17.2 Param Characteristic Sym Min Max Units Conditions Typ No. t Capacitive Loading Specs on Output D100 OSC2 pin рF In XT, HS and LP modes Cosc₂ 15 when external clock is used to drive OSC1. Cio рF D101 All I/O pins and OSC2 (in RC mode) 50 D102 Cb 400 pF SCL. SDA in I²C mode

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.
 - 2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
 - 3: Negative current is defined as current sourced by the pin.

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FIGURE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

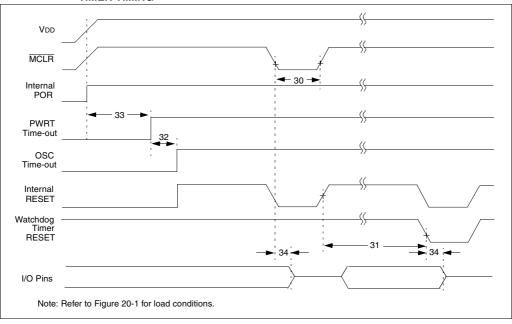


FIGURE 20-5: BROWN-OUT RESET TIMING

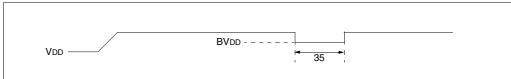


TABLE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2			μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc		_	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or WDT reset	_	_	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	-	_	μs	VDD ≤ BVDD (D005)

These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

21.5 <u>Timing Diagrams and Specifications</u>

FIGURE 21-2: EXTERNAL CLOCK TIMING

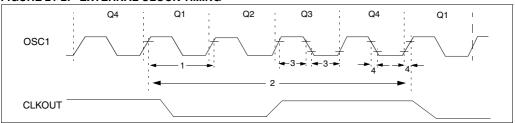


TABLE 21-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC		4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC		4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	_	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μS	LP osc mode
		Oscillator Period	250	_	_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5	_	_	μS	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	200	Tcy	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	_	_	μS	LP oscillator
			15	_	_	ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	_	_	25	ns	XT oscillator
	TosF	Fall Time	_	_	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

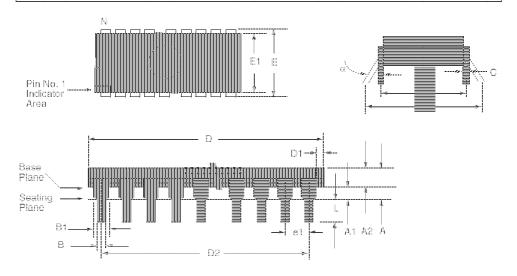
^{*} These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

24.7 28-Lead Ceramic CERDIP Dual In-line with Window (300 mil)) (JW)

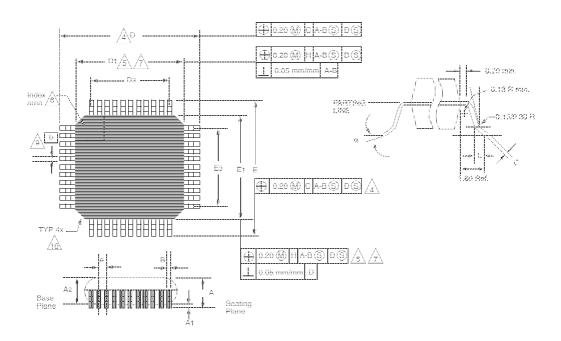
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Ceramic CERDIP Dual In-Line (CDP)						
	Millimeters				Inches	
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
Α	3.30	5.84		.130	0.230	
A1	0.38	_		0.015	_	
A2	2.92	4.95		0.115	0.195	
В	0.35	0.58		0.014	0.023	
B1	1.14	1.78	Typical	0.045	0.070	Typical
С	0.20	0.38	Typical	0.008	0.015	Typical
D	34.54	37.72		1.360	1.485	
D2	32.97	33.07	Reference	1.298	1.302	Reference
Е	7.62	8.25		0.300	0.325	
E1	6.10	7.87		0.240	0.310	
е	2.54	2.54	Typical	0.100	0.100	Typical
eA	7.62	7.62	Reference	0.300	0.300	Reference
eB	_	11.43		_	0.450	
L	2.92	5.08		0.115	0.200	
N	28	28		28	28	
D1	0.13	_		0.005	_	

24.12 44-Lead Plastic Surface Mount (MQFP 10x10 mm Body 1.6/0.15 mm Lead Form) (PQ)

Mote: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic MQFP						
		Millimeters		Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	7°		0°	7°	
Α	2.000	2.350		0.078	0.093	
A1	0.050	0.250		0.002	0.010	
A2	1.950	2.100		0.768	0.083	
b	0.300	0.450	Typical	0.011	0.018	Typical
С	0.150	0.180		0.006	0.007	
D	12.950	13.450		0.510	0.530	
D1	9.900	10.100		0.390	0.398	
D3	8.000	8.000	Reference	0.315	0.315	Reference
E	12.950	13.450		0.510	0.530	
E1	9.900	10.100		0.390	0.398	
E3	8.000	8.000	Reference	0.315	0.315	Reference
е	0.800	0.800		0.031	0.032	
L	0.730	1.030		0.028	0.041	
N	44	44		44	44	
CP	0.102	-		0.004	_	

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